LM813 WiFi and Dual Mode Bluetooth® 4.2 Combi Module Host Controller Interface (HCI) via USB Interface













Datasheet Version

19/FEB/2021 1.2

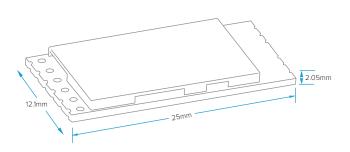
Ordering Options

See last page









Features

1T1R One IPEX Antenna Output 802.11ac MIMO solution for 5G band 433Mbps High Speed WLAN IEEE standards support: IEEE 802.11ac/a/b/g/n WPA/WPA2 certification for WiFi Bluetooth® 4.2 Dual Mode 5v or 3.3v Supply Options USB 2.0 and PCM interface

Support for WiFi/Bluetooth® Coexistence, with both technologies active a slight drop in Wi-Fi throughput is

Bluetooth® adaptive power management mechanism

Linux Support Kernel : 2.6.24 $^{\sim}$ 4.15.17 Supported for Windows 7, 8, 8.1 and 10

CE / FCC Certified Solution

SIG Certification & CCATS due shortly.

RoHS, REACH and WEEE Compliant Solution

Overview

The LM813 Series Combination Module supports both WiFi 802.11ac with data rates up to 433Mbps and Bluetooth® 4.2.

USB Interface module with added terminals for enabling GPIO's and Bluetooth Functions to enable coexistence.

This IPEX, module operates under 2.4GHz or 5Ghz. LM813 is compliant to IEEE 802.11ac/ a/b/g/n, and Bluetooth® v2.1, v3.0 and v4.2 standards.

Currently Bluetooth® includes EDR transmission and supports bandwidths up to 2Mbps, or in HS Mode up to 3Mbps.

The module design is based on a Realtek reference, which LM engineer's have made some modifications, which include; Upgrading the PCB material to -40°C rated components and using a high quality -40°C low temperature crystal. The main IC from Realtek is only rated at 0°C

Our temperature testing is conducted up to -40°C and the module has achieved good results. Although the testing period is only subject to a 72h test period, we have run previous modules using the same brand of BOM material in longer periods of temperature testing. These tests are continuous and enable us to support for -20°C Operating and -30°C Storage Temperature under our own 24 month warranty, from date of dispatch.

We have added a heat resistant coating to the bottom of the module enabling higher temperature protection during the re-flow processing in production.

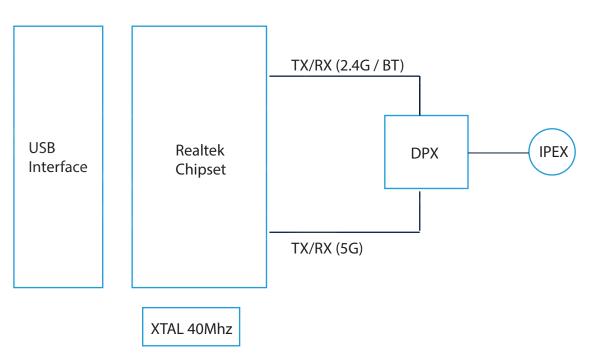
Host Controller Interface (HCI) via USB Interface

General Specification

Wireless

Wireless	
Wireless Standard	WiFi:
	802.11 a/b/g/n/ac
	Bluetooth®:
	v2.1+EDR/v3.0+HS/v4.0/4.2
Module Type	Host Controller Interface (HCI)
OS Compatibility	Linux, and Windows versions to be confirmed.
Security	WiFi;
	WPA, WPA-PSK, WPA2,
	Bluetooth®;
	Simple Paring
Network Architecture	Simple Paring WiFi;
Network Architecture	
Network Architecture	WiFi;
Network Architecture	WiFi; Ad hoc mode (Peer-to-Peer) and Infrastructure mode Software AP; WiFi Direct
Network Architecture Hardware	WiFi; Ad hoc mode (Peer-to-Peer) and Infrastructure mode Software AP; WiFi Direct Bluetooth®;
	WiFi; Ad hoc mode (Peer-to-Peer) and Infrastructure mode Software AP; WiFi Direct Bluetooth®;
Hardware	WiFi; Ad hoc mode (Peer-to-Peer) and Infrastructure mode Software AP; WiFi Direct Bluetooth®; Pico Net; Scatter Net, Low Power Mode(Sniff Mode)
Hardware Chipset	WiFi; Ad hoc mode (Peer-to-Peer) and Infrastructure mode Software AP; WiFi Direct Bluetooth®; Pico Net; Scatter Net, Low Power Mode(Sniff Mode) Realtek Chipset

Block Diagram





Host Controller Interface (HCI) via USB Interface

General Specification (Continued)

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NI Characteristics	
Range (in open space)	WiFi:
	Up to 180m
	Bluetooth®:
	Up to 10m
Data Transfer Rate	WiFi:
	802.11b: 1, 2, 5.5, 11Mbps; 802.11g: 6, 9, 12, 18, 24, 36, 48, 433Mbps;
	802.11n MCS0 to 7 for HT20MHz, MCS0 to 7 for HT40MHz
	Bluetooth®:
	Basic Rate 1Mbps; Enhanced Rate 2, 3Mbps;
	High Speed 6, 9, 12, 18, 24, 36, 48, 54Mbps
Frequency	2.4GHz and 5GHz ISM Band
Modulation Scheme	WiFi:
	CCK, DQPSK, DBPSK, BPSK, QPSK,16QAM, 64QAM, 256QAM
	Bluetooth®:
	8DPSK, π/4 DQPSK, GFSKFSK
Spread Spectrum	WiFi:
	IEEE 802.11b: CCK (Complementary Code Keying)
	IEEE 802.11g/n/a/ac:OFDM (Orthogonal Frequency Division Multiplexing)
	Bluetooth®:
	FHSS (Frequency Hopping Spread Spectrum)
Antenna	IPEX Antenna x 2
Security	WPA, WPA2
RF Output Power (tolerance ± 2dBm)	WiFi
	17dBm - 802.11b@CCK 11Mbps
	15dBm - 802.11g@OFDM 54Mbps
	13dBm - 802.11n@MCS7_HT20
	13dBm - 802.11n@MCS7_HT40
	13dBm – 802.11a@OFDM 54Mbps
	9dBm - 802.11ac@NSS1 MCS9_BW20, BW40, BW80
	Bluetooth
	May LOdDes

Max + 8dBm

Host Controller Interface (HCI) via USB Interface

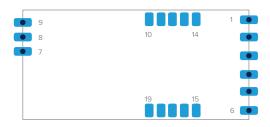
Receiver Sensitivity	WiFi
	-80dBm – 802.11b@11Mbps
	-71dBm – 802.11g@54MBps
	-67dBm - 802.11n@MCS7_BW20
	-64dBm - 802.11n@MCS7_BW40
	-57dBm - 802.11ac@NSS1_MCS9_BW20
	-54dBm - 802.11ac@NSS1_MCS9_BW40
	-51dBm - 802.11ac@NSS1_MCS9_BW80
	Bluetooth
	-89dBm@1Mbps
	-90dBm@2Mbps
	-83dBm@3Mbps
Operating Temperature	-20°C to +85°C ambient temperature 0 to 95 % (non-condensing)
Storage Temperature	-30°C to +95°C ambient temperature 0 to 95 % (non-condensing)
Dimensions (L x W x H)	25mm x 12mm x 2.05mm
Weight	0.82 g
Certifications	See our website for certifications
Compliance	RoHS, REACH and WEEE

Power Consumption

DC power for 5V	Performance		DC power for 3.3V	Performance	
Description	Тур	Units	Description	Тур	Units
Off	10	uA	Off	16	uA
Unassociated idle	40	mA	Unassociated idle	90	mA
Associated idle for 2.4GHz band	70	mA	Associated idle for 2.4GHz band	141	mA
Data transfer for 2.4GHz	103	mA	Data transfer for 2.4GHz	168	mA
Note: Data transfer test using the I	inux driver: Linux_v4.3.6_	11841.20140714	Note: Data transfer test using the L	inux driver: Linux_v4.3.6_	11841.20140714

Host Controller Interface (HCI) via USB Interface

Pin Outs

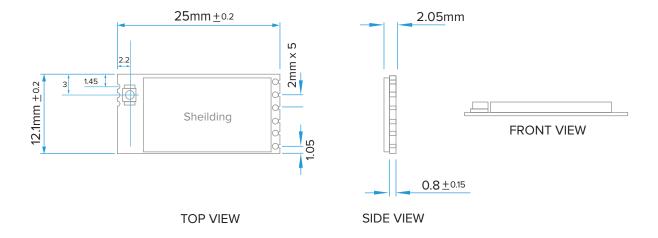


Pin Assignments

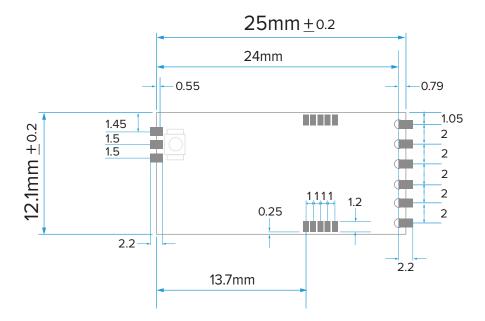
Pin	Signal	Type	Description
1	BT_LED	Output	BT LED Pin(Active Low)
2	VDD	Power	3.3V or 5V by factory option
3	HSDM	I/O	High-Speed USB D- Signal
4	HSDP	I/O	High-Speed USB D+ Signal
5	GND		Ground
6	WL_LED	I/O	WLAN LED Pin(Active Low), General Purpose Input/ Output Pin
7	GND		Ground
8	RFIO_OUT	RF	WLAN(2.4G/5G)/BT RF port (if don't using IPEX connector)
9	GND		Ground
10	BT_WAKE_HOST	Output	Signal from module to wake up host, refer driver source code for details.
11	GPIO2	I/O	General Purpose Input/ Output Pin
12	CHIP_EN	Input	This Pin Can externally shut down the RTL8821CU-CG(No Extra Power Switch Required).
13	GPIO1	I/O	General Purpose Input/ Output Pin
14	BT_DIS	Input	Shared with GPIO11. This pin can externally shut down the RTL8821CU-CG BT function
			when BT_DIS is pulled Low. When this pin is pulled low. USB interface will be also
			disabled. This pin can be also defined as the BT Radio-off function with host interface
			remaining connected
15	GPIO8	I/O	WLAN LED Pin(Active Low), shared with GPIO8 General Purpose Input/ Output Pin
16	HOST_WAKE_BT	Input	Signal from host to wake up module, refer driver source code for details.
17	WL_DIS	Input	Shared with GPIO9. This pin can externally shut down the RTL8821CU-CG WLAN
			function when WL_DIS is pulled Low. When this pin is pulled low. USB interface will be
			also disabled. This pin can also be configured as the WLAN Radio-off function with host
			interface remaining connected
18	HOST_WAKE_WL	Input	

Host Controller Interface (HCI) via USB Interface

Physical Dimensions

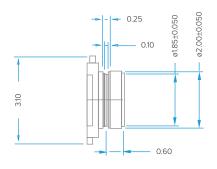


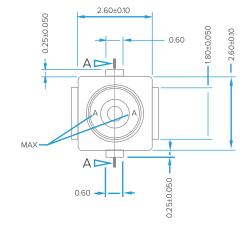
PCB Layout

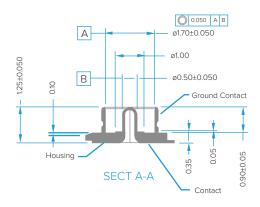


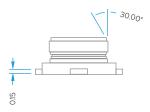
Host Controller Interface (HCI) via USB Interface

RF Connector Dimensions









Host Controller Interface (HCI) via USB Interface

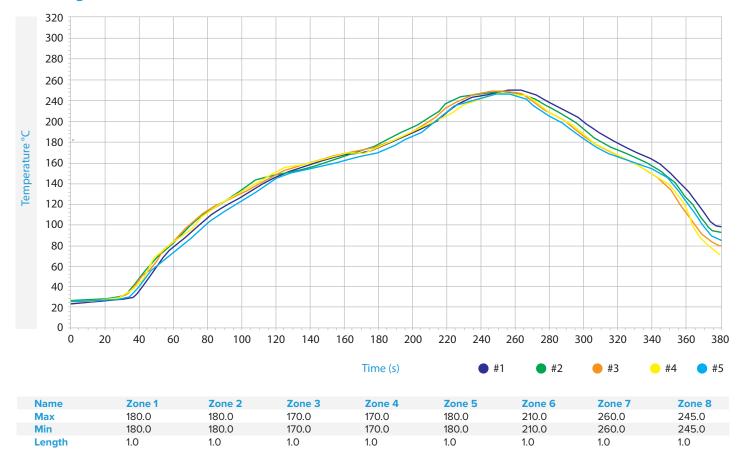
PCB Drying Conditions

Please refer below to the conditions for drying before the solder reflow processes. (Extracted from IPC/JEDEC J-STD-033B.1)

- 1. If the system PCBA is double side design please reflow the side without this module first.
- 2. Don't let the solder machine temperature over 250 °C or follow solder paste vender's recommended temperature.
- 3. The Ramp-up temperature speed is 1"4 °C per second, the Ramp-down temperature speed is 1"4 °C per second.
- 4. This temperature reflow chart is for reference only, it depends on the manufaturing machine's characters requirement.

Bake @ 125 °C		Bake @ 90 °C		Bake @ 40 °C	
Exceeding floor Life by > 72h	Exceeding floor Life by ≤ 72h	Exceeding floor Life by > 72h	Exceeding floor Life by ≤ 72h	Exceeding floor Life by > 72h	Exceeding floor Life by ≤ 72h
9 hours	7 hours	33 hours	23 hours	13 days	9 days

Soldering Reflow Chart



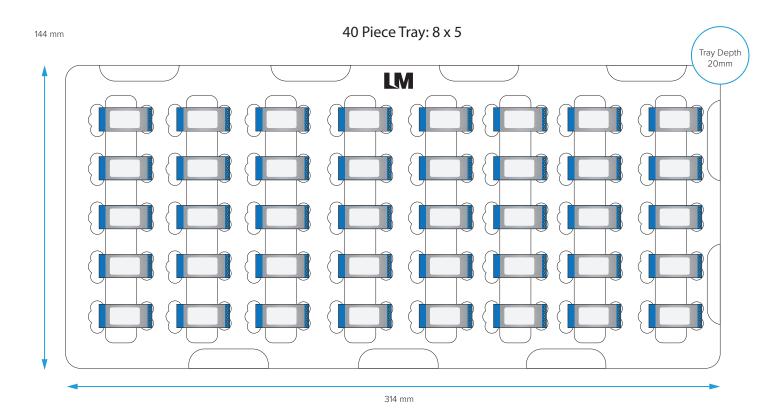
Probe	Liquidus Line		Maximum / M	1 inimum	Slope
	Rising 110.00-190.00	Above 230.0	Max	Min	Positive Negative
# 1	119.00	47.50	245.50	27.30	2.56 -1.69
# 2	116.50	49.00	247.10	27.70	2.69 -1.60
# 3	116.00	46.50	245.80	29.30	2.04 -1.57
<u>#</u> 4	117.00	46.50	244.90	29.20	2.60 -1.31
# 5	119.50	50.00	248.10	29.60	2.44 -1.64



Host Controller Interface (HCI) via USB Interface

Tray Packaging

Tray Dimensions



Quantities

- 40 modules per Tray
- 3 Trays per Inner Box
- 120 modules per Inner Box
- 8 Inner Boxes per Outer Carton
- 960 modules per Outer Carton

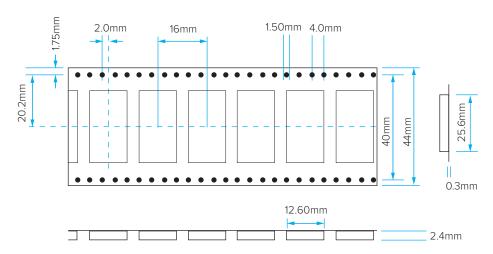
Notes

- Anti-Static PS Tray, Black.
- Material Thickness: 1mm
- Height of Tray: 20mm
- Carton Dimensions (L x W x H):
 340mm x 290mm x 385mmm

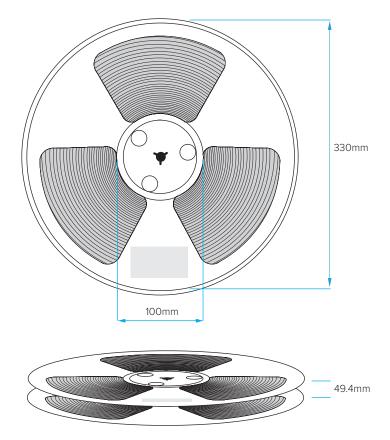
Host Controller Interface (HCI) via USB Interface

Tape and Reel Packaging

Tape Dimensions



Reel Dimensions



Quantities

- 1500 modules per Tape & Reel
- 1 Tape & Reel per Inner Box
- 5 Inner Boxes per Outer Carton
- 7500 modules per Outer Carton

Notes

- Inner Box Dimensions (L x W x H):
 360mm x 360mm x 60mm
- Outer Carton Dimensions (L x W x H):
 395mm x 360mm x 305mm

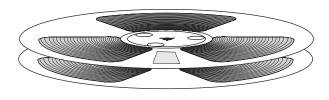
Host Controller Interface (HCI) via USB Interface

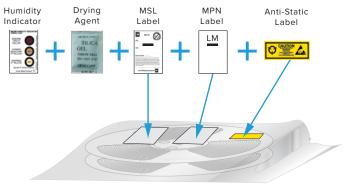
Packaging for Tape & Reel / Tray

The Tape & Reel / Tray are inserted into an anti-static vacuum bag with a Humidity Indicator Card and Drying Agent. On the outside of the vacuum bag are MSL (Moisture Sensitivity Levels), MPN and an Anti-Static Labels.

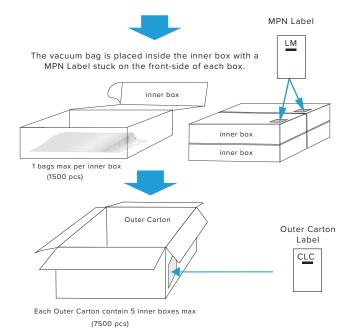
Tape & Reel

Reels are placed within a vacuum bag.



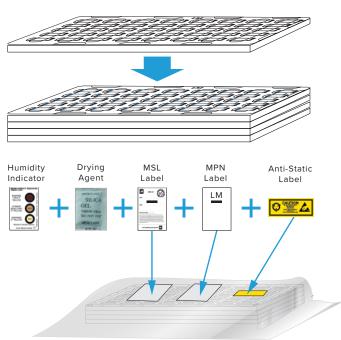


Vacuum bag.

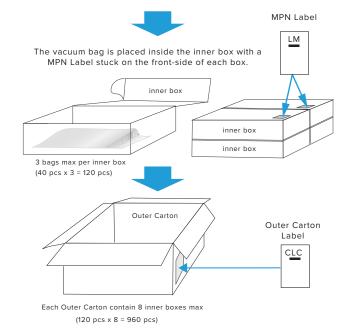


Tray

Trays are stacked with an empty tray on the top and placed within a vacuum bag.



Vacuum bag



LM813 WiFi and Dual Mode Bluetooth® Combination Module Host Controller Interface (HCI) via USB Interface

Datasheet Version Notes

v1.2 22 JAN 2021 Added version notes to datasheet, branding updates.

Host Controller Interface (HCI) via USB Interface

Ordering Options

The state of the s	813-0813 TRAY	5V Module with IPEX Connector MOD SMT HCI 802.11ac 1T1R - BT4.2 -20c 5v IPEX TRAY	ETSI
The state of the s	813-0814 SAMPLE PACK	5V Module with IPEX Connector MOD SMT HCI 802.11ac 1T1R - BT4.2 -20c 5v IPEX TRAY SP	ETSI
The state of the s	813-0815 TAPE & REEL	5V Module with IPEX Connector MOD SMT HCI 802.11ac 1T1R - BT4.2 -20c 5v IPEX T&R	ETSI
Constitution of the second of	813-0816 US TRAY	5V Module with IPEX Connector MOD SMT HCI 802.11ac 1T1R - BT4.2 -20c 5v IPEX TRAY	US
The state of the s	813-0817 US SAMPLE PACK	5V Module with IPEX Connector MOD SMT HCI 802.11ac 1T1R - BT4.2 -20c 5v IPEX TRAY SP	US
Constitution of the second	813-0818 US TAPE & REEL	5V Module with IPEX Connector MOD SMT HCI 802.11ac 1T1R - BT4.2 -20c 5v IPEX T&R	US

[•] Product User Guides, Manuals and Configuration Software can be downloaded via our website - http://www.lm-technologies.com/downloads